	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	389	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with maintenance$1 with manag$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:09	
2	BRS	1178	702/176,177,178,184,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:19	
3	BRS	0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and semiconductor$1 same process$3 with parameter$1 and prevent$3 with maintenance$1 and (validat$3 or evaluat$3 or estimat$3) with tim$3 with cost$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:19	
4	BRS	65	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	6	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and (estimat$3 or validat$3 or evaluat$3 or predict$3) with qualit$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	
6	BRS	6	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	0	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 with parameter$1 and process$3 with parameter$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
8	BRS	8	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
9	BRS	65	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	18	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	
11	BRS	4	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) with measur$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	17	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
13	BRS	4	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
14	BRS	9	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:35	
15	BRS	76	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	51	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	
17	BRS	24	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6) and (compar$4 or differen$2) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
18	BRS	15	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6) and (compar$4 or differen$2) with equipment$1 with process$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS	2	(record$3 or stor$3 or sav$3 or database) with equipment with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3) with test$3 with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and statistic$4 with (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	
20	BRS	4	(record$3 or stor$3 or sav$3 or database) with equipment with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3) with test$3 with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
21	BRS	24	(record$3 or stor$3 or sav$3 or database) with equipment$1 with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3 or predict$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	
22	BRS	14	(record$3 or stor$3 or sav$3 or database) with equipment$1 with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3 or predict$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3) and statistic$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS	3	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 with product$1 and t-test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
24	BRS	18	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with maintenance$1 with manag$6 and optimiz$5 with performance	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:13	
25	BRS	32542	(determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:15	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS	18	(determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1) and optimiz$3 with qualit$3 with performance$1 with product$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:17	
27	BRS	0	(determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1) and select$3 with process$3 with parameter$1 same optimiz$3 with qualit$3 with performance$1 with product$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
28	BRS	2032	702/176,177,178,183,184,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:20	
29	BRS	5714	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:19	
30	BRS	7637	702/176,177,178,183,184,187.ccls. or 700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:23	
31	IS&R	2	("6745094").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:22	
32	BRS	0	"6745094".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	379	(702/176,177,178,183,184,187.ccls. or 700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and (determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:24	
34	BRS	21	(702/176,177,178,183,184,187.ccls. or 700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and (determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1) with process$3 with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS	94	(702/176,177,178,183,184,187.ccls. or 700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.) and (determin$3 or detect$3 or monitor$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with (defect$1 or error$1 or fail$4 or malfunction$2 or anomal$3 or problem$1)	US-PGPUB	2005/10/28 15:25	
36	BRS	74	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	7	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and (estimat$3 or validat$3 or evaluat$3 or predict$3) with qualit$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:29	
38	BRS	7	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
39	BRS	0	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 with parameter$1 and process$3 with parameter$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
40	BRS	9	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:30	
41	BRS	74	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
42	BRS	26	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:31	
43	BRS	8	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) with measur$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
44	BRS	25	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
45	BRS	5	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS	10	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:34	
47	BRS	10	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (condiction$1 or status or state$1) with equipment$1 and database$1 and (record$3 or stor$3 or sav$3) and (predict$3 or inspect$3 or estimat$3 or validat$3 or evaluat$3) and equipments	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:35	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
48	BRS	87	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	
49	BRS	57	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
50	BRS	29	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6) and (compar$4 or differen$2) with equipment$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
51	BRS	19	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 and (record$3 or stor$3 or sav$3 or database) with equipment with (parameter$1 or measur$6) and (record$3 or stor$3 or sav$3 or database) with process$3 with (parameter$1 or measur$6) and (compar$4 or differen$2) with equipment$1 with process$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
52	BRS	3	(record$3 or stor$3 or sav$3 or database) with equipment with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3) with test$3 with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and statistic$4 with (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:37	
53	BRS	5	(record$3 or stor$3 or sav$3 or database) with equipment with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3) with test$3 with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
54	BRS	28	(record$3 or stor$3 or sav$3 or database) with equipment$1 with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3 or predict$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	
55	BRS	17	(record$3 or stor$3 or sav$3 or database) with equipment$1 with (status$2 or condition$1 or state$1) and (inspect$3 or evaluat$3 or estimat$3 or validat$3 or predict$3) with (semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with product$1 and (analyz$3 or analys$3) and statistic$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
56	BRS	9	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 with product$1 and t-test$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
57	BRS	4	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 with product$1 and t-test$3 and process$3 with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	
58	BRS	0	(semiconductor$1 or wafer$1 or chip$1 or die$1 or IC$1 or (integrated adj circuit$1)) with qualit$3 with product$1 and t-test$3 and process$3 with parameter$1 and optimiz$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/10/28 15:40	

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
1			US 20050203654 A1	20050915	18	System and method for scheduling manufacturing jobs for a semiconductor manufacturing tool	700/100	700/108	700/108
2	X		US 20050197728 A1	20050908		FEATURE TARGETED INSPECTION	700/110	700/121	700/121
3	X		US 20050177269 A1	20050811	26	Method for dynamic sensor configuration and runtime execution	700/121		700/121
4	X		US 20050177263 A1	20050811		System and method for monitoring wafer furnace production efficiency	700/108		700/108
5	X		US 20050171627 A1	20050804		Method and apparatus for monitoring tool performance	700/121		700/121
6	X		US 20050171626 A1	20050804		System, method, and medium for monitoring performance of an advanced process control system	700/108		700/108

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
7	X		US 20050159911 A1	20050721		Method and apparatus for automatic sensor installation	702/104	700/121	700/121
8	X		US 20050137737 A1	20050623		Integrated circuit card system and application loading method	700/121		700/121
9	X		US 20050125090 A1	20050609		Method and apparatus for evaluating processing apparatus status and predicting processing result	700/108	438/14; 700/121	700/108; 700/121
10	X		US 20050122510 A1	20050609		System and method for process variation monitor	356/237.2	382/145; 700/121	700/121
11	X		US 20050090923 A1	20050428		Method for monitoring a batch system	700/109	257/E21.525; 700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
12	X		US 20050090922 A1	20050428		Test circuit, semiconductor product wafer having the test circuit, and method of monitoring manufacturing process using the test circuit	700/108	438/14	700/108
13	X		US 20050085932 A1	20050421		Technique for evaluating a fabrication of a semiconductor component and wafer	700/90	700/108	700/108
14	X		US 20050085928 A1	20050421		System and method for implementing logic control in programmable controllers in distributed control systems	700/18	700/19; 700/20; 700/276; 700/277; 700/278; 700/86; 700/87	700/19
15	X		US 20050075830 A1	20050407		Process parameter based I/O timing programmability using electrical fuse elements	702/176		702/176

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
16	X		US 20050071031 A1	20050331		Algorithms tunning for dynamic lot dispatching in wafer and chip probing	700/101	700/100; 700/121	700/121
17	X		US 20050055121 A1	20050310		System and methed for effective field loss analysis for semiconductor wafers	700/110	700/121	700/121
18	X		US 20050054268 A1	20050310		Methods for detecting transitions of wafer surface properties in chemical mechanical polishing for process status and control	451/5	700/121	700/121
19	X		US 20050049834 A1	20050303		Non-invasive system and method for diagnosing potential malfunctions of semiconductor equipment components	702/183		702/183

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20	X		US 20050049740 A1	20050303		Method, system and program product providing a configuration specification language having clone latch support	700/121		700/121
21	X	X	US 20050038544 A1	20050217	7	MANAGEMENT SYSTEM OF MONITOR WAFERS	700/108	700/121; 700/80	700/108; 700/121
22	X		US 20050027482 A1	20050203		Method for estimating the quality of wood chips	702/183		702/183
23	X		US 20050027388 A1	20050203		Reducing asymmetrically deposited film induced registration error	700/121		700/121
24	X		US 20050010890 A1	20050113	22	Design-based monitoring	716/19	700/121; 716/21; 716/4	700/121
25	X		US 20040260420 A1	20041223	51	Processing method and processing system	700/121		700/121

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26	X		US 20040254761 A1	20041216		Operation monitoring method for treatment apparatus	702/182	702/183	702/183
27	X		US 20040254669 A1	20041216		Automatic recognition of locator die in partial wafermap process	700/121	382/151	700/121
28	X		US 20040225401 A1	20041111		Computer-implemented method and carrier medium configured to generate a set of process parameters and/or a list of potential causes of deviations for a lithography process	700/121		700/121
29	X		US 20040199282 A1	20041007		Method for determining a preceding wafer, method for determining a measuring wafer, and method for adjusting the number of wafers	700/121		700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
30	X		US 20040181303 A1	20040916		Relatively unique ID in integrated circuit	700/115	380/44; 700/121	700/121
31	X		US 20040172152 A1	20040902		Sorting a group of integrated circuit devices for those devices requiring special testing	700/121		700/121
32	X		US 20040167656 A1	20040826		Production managing system of semiconductor device	700/121		700/121
33	X		US 20040148136 A1	20040729		Management supporting apparatus, management supporting system, management supporting method, management supporting program, and a recording medium with the program recorded therein	702/188	702/184	702/184
34	X		US 20040133294 A1	20040708		Defect alarm system and method	700/110	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
35	X		US 20040117055 A1	20040617		Configuration and method for detecting defects on a substrate in a processing tool	700/121	700/110	700/121
36	X		US 20040111176 A1	20040610		In-situ randomization and recording of wafer processing order at process tools	700/121		700/121
37	X		US 20040107020 A1	20040603		Fabrication system and fabrication method	700/121		700/121
38	X		US 20040088071 A1	20040506		Aligner evaluation system, aligner evaluation method, a computer program product, and a method for manufacturing a semiconductor device	700/121		700/121
39	X		US 20040059456 A1	20040325		Correlating an inline parameter to a device operation parameter	700/121	257/E21.525	700/121

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40	X		US 20040039473 A1	20040226		Integrated circuit profile value determination	700/121		700/121
41	X		US 20040029029 A1	20040212		Error reduction in semiconductor processes	430/30	355/44; 355/52; 355/56; 430/22; 430/311; 700/121; 700/65; 702/122	700/121
42	X		US 20040015256 A1	20040122		Feedback method utilizing lithographic exposure field dimensions to predict process tool overlay settings	700/121	716/21	700/121
43	X		US 20040006404 A1	20040108		Permanent chip ID using FeRAM	700/115	700/121	700/121
44	X		US 20030236586 A1	20031225		Method for failure analysis and system for failure analysis	700/110	700/121	700/121

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45	X		US 20030225475 A1	20031204		Method and system for estimating microelectronic fabrication product yield	700/121	700/108	700/108; 700/121
46	X		US 20030220708 A1	20031127		Integrated equipment set for forming shallow trench isolation regions	700/121	438/690	700/121
47	X		US 20030217343 A1	20031120		Manufacturing method and apparatus to avoid prototype-hold in ASIC/SOC manufacturing	716/4	700/121	700/121
48	X		US 20030212469 A1	20031113		METHOD FOR AUTOMATICALLY CONTROLLING DEFECT - SPECIFICATION IN A SEMICONDUCTOR MANUFACTURING PROCESS	700/121	438/14; 700/110	700/121
49	X		US 20030200056 A1	20031023		Semiconductor device analysis system	702/183		702/183

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
50	X		US 20030199108 A1	20031023		Method of monitoring and/or controlling a semiconductor manufacturing apparatus and a system therefor	438/14	118/663; 156/345.24; 257/E21.525; 700/121	700/121
51	X		US 20030191550 A1	20031009		Method for using data regarding manufacturing procedures integrated circuits (IC's) have undergone, such as repairs, to select procedures the IC's undergo, such as additional repairs	700/121		700/121
52	X		US 20030187535 A1	20031002		Throughput analysis system and method	700/108	700/104; 700/111	700/108
53	X		US 20030182079 A1	20030925		System and method to provide measurement capabilities for both single-ended and differential signals with software switching	702/177		702/177

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54	X		US 20030171896 A1	20030911		Method and system for graphical evaluation of IDDQ measurements	702/183		702/183
55	X		US 20030171836 A1	20030911	52	Semiconductor manufacturing apparatus, management apparatus therefor, component management apparatus therefor, and semiconductor wafer storage vessel transport apparatus	700/108	702/182; 702/187	700/108; 702/187
56	X		US 20030163217 A1	20030828		Semiconductor manufacturing apparatus and its diagnosis apparatus and operating system	700/108	700/121	700/108; 700/121
57	X		US 20030154052 A1	20030814		Method for diagnosing life of manufacturing equipment using rotary machine	702/184		702/184

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58	X		US 20030153995 A1	20030814		Semiconductor manufacturing system and control method thereof	700/101	700/121	700/121
59	X		US 20030149547 A1	20030807		Method for diagnosing failure of a manufacturing apparatus and a failure diagnosis system	702/183		702/183
60	X		US 20030139839 A1	20030724		Method of sorting a group of integrated circuit devices for those devices requiring special testing	700/115	700/109; 700/116; 700/121	700/121
61	X		US 20030135295 A1	20030717		Defect source identifier with static manufacturing execution system	700/108	700/109; 700/110; 700/117; 700/121	700/108; 700/117; 700/121

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62	X		US 20030109945 A1	20030612		Apparatus and method for automatically controlling semiconductor manufacturing process in semiconductor factory automation system	700/95	700/109; 700/121	700/121
63	X		US 20030105547 A1	20030605		SYSTEM AND METHOD FOR MODIFYING ENCLOSED AREAS FOR ION BEAM AND LASER BEAM BIAS EFFECTS	700/121	438/4	700/121
64	X		US 20030100970 A1	20030529		Method and system of monitoring apparatuses of manufacturing IC	700/108	700/109; 700/121	700/108; 700/121
65	X		US 20030065484 A1	20030403		AC defect detection and failure avoidance power up and diagnostic system	702/187		702/187
66	X		US 20030060916 A1	20030327		Automatic production quality control method and system	700/121	700/109	700/121

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67	X		US 20030055523 A1	20030320	15	User configurable multivariate time series reduction tool control method	700/108	257/E21.525; 700/175; 700/51; 700/83; 702/185	700/108; 700/175
68	X		US 20030037309 A1	20030220		Management system and management method of semiconductor exposure apparatuses	716/21	700/121	700/121
69	X		US 20030033046 A1	20030213	23	Method and system for manufacturing semiconductor devices	700/121	716/21	700/121
70	X		US 20030018406 A1	20030123	23	Method and system for manufacturing semiconductor devices	700/121	716/21	700/121
71	X		US 20030014146 A1	20030116		Dangerous process/pattern detection system and method, danger detection program, and semiconductor device manufacturing method	700/121		700/121

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72	X		US 20030014145 A1	20030116	18	Integration of fault detection with run-to-run control	700/121	700/108; 700/110	700/108; 700/121
73	X		US 20020198682 A1	20021226	8	Method and apparatus for determining end-point in a chamber cleaning process	702/184		702/184
74	X		US 20020193899 A1	20021219	18	Dynamic metrology schemes and sampling schemes for advanced process control in semiconductor processing	700/108	257/E21.525; 700/121; 700/97	700/108; 700/121
75	X		US 20020183884 A1	20021205		Method for continuous, non lot-based integrated circuit manufacturing	700/115	700/121	700/121
76	X		US 20020165636 A1	20021107	24	Systems and methods for metrology recipe and model generation	700/121		700/121
77	X		US 20020143424 A1	20021003		Device and method of selecting photomask manufacturer based on received data	700/121		700/121

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78	X		US 20020123818 A1	20020905		Production managing system of semiconductor device	700/121		700/121
79	X		US 20020111759 A1	20020815		Failure analysis device and failure analysis method	702/82	700/108; 700/109; 700/110	700/108
80	X		US 20020107666 A1	20020808		Maintenance system for analyzing instrument	702/184		702/184
81	X		US 20020103564 A1	20020801		Methods and systems for determining a composition and a thickness of a specimen	700/121		700/121
82	X		US 20020103563 A1	20020801		Method of manufacturing a semiconductor device and manufacturing system	700/121		700/121

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83	X		US 20020082740 A1	20020627		Method for using data regarding manufacturing procedures integrated circuits (IC's) have undergone, such as repairs, to select procedures the IC's will undergo, such as additional repairs	700/121		700/121
84	X		US 20020072878 A1	20020613		Deterioration diagnostic method and equipment thereof	702/183		702/183
85	X		US 20020068989 A1	20020606		Method and apparatus for designing integrated circuits and storage medium for storing the method	700/121		700/121
86	X		US 20020062162 A1	20020523	15	User configurable multivariate time series reduction tool control method	700/108	257/E21.525; 700/51	700/108

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87	X		US 20020059012 A1	20020516		Method of manufacturing semiconductor devices	700/121	257/E21.525	700/121
88	X		US 20020059010 A1	20020516		Failure analyzing device for semiconductors	700/110	257/E21.525; 700/109; 700/117; 700/121	700/117; 700/121
89	X		US 20020055801 A1	20020509		Fault detection and virtual sensor methods for tool fault monitoring	700/111	700/117; 700/175; 700/178	700/117; 700/175; 700/178
90	X		US 20020035447 A1	20020321	35	Remote diagnosing system for semiconductor manufacturing equipment and a remote diagnosing method	702/188	257/E21.525; 438/14; 700/108; 700/121; 700/2; 702/183	700/108; 700/121; 702/183
91	X		US 20020026251 A1	20020228		System and method for monitoring and controlling gas plasma processes	700/67	700/121; 700/68	700/121
92	X		US 20010051839 A1	20011213		DIFFERENTIAL PROCESS CONTROL METHOD	700/121		700/121

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93	Nakano, Hirotaka et al.									
94	Sugikawa, Yutaka									